

ND2012 SERIES

 Siliconix
incorporated

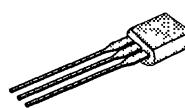
N-Channel Depletion-Mode MOS Transistors

PRODUCT SUMMARY

PART NUMBER	V _{(BR)DSV} (V)	r _{DS(ON)} (Ω)	I _D (A)	PACKAGE
ND2012L	200	12	0.16	TO-92
ND2012E	200	12	0.22	TO-206AC

Performance Curves: VDDQ20 (See Section 7)

TO-92

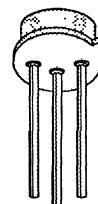


BOTTOM VIEW

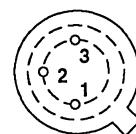


1 SOURCE
2 GATE
3 DRAIN

TO-206AC (TO-52)



BOTTOM VIEW



1 SOURCE
2 GATE
3 DRAIN & CASE

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	ND2012L	ND2012E ²	UNITS
Drain-Source Voltage	V _{DS}	200	200	V
Gate-Source Voltage	V _{GS}	±30	±20	
Continuous Drain Current	T _A = 25°C	I _D	0.16	A
	T _A = 100°C		0.10	
Pulsed Drain Current ¹	I _{DM}	0.8	0.8	
Power Dissipation	T _A = 25°C	P _D	0.80	W
	T _A = 100°C		0.32	
Operating Junction and Storage Temperature	T _J , T _{stg}	-55 to 150		°C
Lead Temperature (1/16" from case for 10 seconds)	T _L	300		

THERMAL RESISTANCE

THERMAL RESISTANCE	SYMBOL	ND2012L	ND2012E	UNITS
Junction-to-Ambient	R _{thJA}	156	400	°C/W

¹Pulse width limited by maximum junction temperature

²Reference case for all temperature testing

ELECTRICAL CHARACTERISTICS ¹			LIMITS			
PARAMETER	SYMBOL	TEST CONDITIONS	TYP ²	ND2012		UNIT
				MIN	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSV}	V _{GS} = -8 V, I _D = 10 µA	220	200		V
Gate-Source Cutoff Voltage	V _{GS(OFF)}	V _{DS} = 5 V, I _D = 10 µA	-3	-1.5	-4	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V V _{GS} = ±20 V T _J = 125°C	±0.1 ±5		±10 ±50	nA
Drain Cutoff Current	I _{D(OFF)}	V _{DS} = 160 V V _{GS} = -8 V T _J = 125°C	0.2 5		1 200	µA
Drain Saturation Current ³	I _{DSS}	V _{DS} = 10 V, V _{GS} = 0 V	400	30		mA
Drain-Source On-Resistance ³	r _{DS(ON)}	V _{GS} = 2 V, I _D = 20 mA	7			
		V _{GS} = 0 V I _D = 20 mA T _J = 125°C	8 15		12 30	Ω
Forward Transconductance	g _{FS}	V _{DS} = 7.5 V, I _D = 20 mA	55			mS
Common Source Output Conductance ³	g _{OS}		75			µS
DYNAMIC						
Input Capacitance	C _{iss}	V _{DS} = 25 V V _{GS} = -5 V f = 1 MHz	35		100	pF
Output Capacitance	C _{oss}		10		20	
Reverse Transfer Capacitance	C _{rss}		2		5	
SWITCHING						
Turn-On Time	t _{d(ON)}	V _{DD} = 25 V, R _L = 1250 Ω I _D = 20 mA, V _{GEN} = -5 V R _G = 25 Ω (Switching time is essentially independent of operating temperature)	20			ns
	t _r		20			
Turn-Off Time	t _{d(OFF)}		10			
	t _f		10			

NOTES: 1. T_A = 25 °C unless otherwise noted, T_C = 25 °C for ND2012E.

2. For design aid only, not subject to production testing.

3. Pulse test; PW = 300 µs, duty cycle ≤ 2%.